



T3MNS010



200V N-Channel MOSFETs

General Description

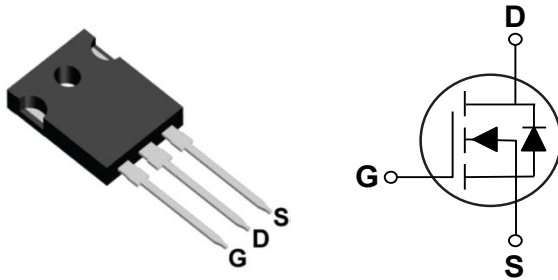
These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

| BV_{DSS} | $R_{DS(ON)}$ | I_D |
|------------|--------------|-------|
| 200 V | 10 mΩ | 150 A |

Features

- $R_{DS(ON)} \leq 10m\Omega @ V_{GS}=10V$
- Improved dv/dt Capability
- Fast Switching
- Green Device Available

TO-247-3L Pin Configuration



Applications

- UPS
- Inverter

Absolute Maximum Ratings $T_C=25^\circ C$ unless otherwise noted

| Symbol | Parameter | Rating | Units |
|--------------|---|------------|------------|
| V_{DS} | Drain-Source Voltage | 200 | V |
| V_{GS} | Gate-Source Voltage | ± 30 | V |
| I_D | Drain Current – Continuous ($T_A=25^\circ C$) | 150 | A |
| I_{DM} | Drain Current – Pulsed (NOTE 1) | 450 | A |
| EAS | Single Pulse Avalanche Energy (NOTE 2) | 1600 | mJ |
| P_D | Power Dissipation ($T_C=25^\circ C$) | 277 | W |
| T_J | Operating Junction Temperature Range | -55 to 150 | $^\circ C$ |
| T_{STG} | Storage Temperature Range | -55 to 150 | $^\circ C$ |
| Marking Code | | NS010 | |

Thermal Characteristics

| Symbol | Parameter | Rating | Unit |
|-----------------|--|--------|--------------|
| $R_{\theta JA}$ | Thermal Resistance Junction to Ambient | 40 | $^\circ C/W$ |
| $R_{\theta JC}$ | Thermal Resistance Junction to Case | 0.45 | $^\circ C/W$ |

**Electrical Characteristics (T_J=25°C, unless otherwise noted)****Off Characteristics**

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|-------------------|--------------------------------|--|------|------|------|------|
| BV _{DSS} | Drain-Source Breakdown Voltage | V _{GS} =0V, I _D =250uA | 200 | --- | --- | V |
| I _{DSS} | Drain-Source Leakage Current | V _{DS} =200V, V _{GS} =0V | --- | --- | 1 | uA |
| I _{GSS} | Gate-Source Leakage Current | V _{GS} =±20V, V _{DS} =0V | --- | --- | ±100 | nA |

On Characteristics

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|---------------------|-----------------------------------|--|------|------|------|------|
| R _{DS(ON)} | Static Drain-Source On-Resistance | V _{GS} =10V, I _D =80A | --- | --- | 10 | mΩ |
| V _{GS(th)} | Gate Threshold Voltage | V _{GS} =V _{DS} , I _D =250uA | 3.6 | --- | 5.0 | V |

Dynamic and switching Characteristics

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|---------------------|------------------------------|---|------|-------|------|------|
| Q _g | Total Gate Charge | V _{DD} =100V, V _{GS} =10V, I _D =80A | --- | 170 | --- | nC |
| Q _{gs} | Gate-Source Charge | | --- | 30 | --- | |
| Q _{gd} | Gate-Drain Charge | | --- | 50 | --- | |
| T _{d(on)} | Turn-On Delay Time | V _{DS} =50V, R _G =2.5Ω, I _D =80A, V _{GS} =10V | --- | 90 | --- | nS |
| T _r | Rise Time | | --- | 140 | --- | |
| T _{d(off)} | Turn-Off Delay Time | | --- | 220 | --- | |
| T _f | Fall Time | | --- | 180 | --- | |
| C _{iss} | Input Capacitance | V _{DS} =25V, V _{GS} =0V, F=1MHz | --- | 15000 | --- | pF |
| C _{oss} | Output Capacitance | | --- | 1000 | --- | |
| C _{rss} | Reverse Transfer Capacitance | | --- | 420 | --- | |

Drain-Source Diode Characteristics and Ratings

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|-----------------|-------------------------------|---|------|------|------|------|
| I _S | Continuous Body Diode Current | | --- | --- | 150 | A |
| I _{SM} | Pulsed Diode Forward Current | | --- | --- | 450 | A |
| V _{SD} | Diode Forward Voltage | V _{GS} =0V, I _S =80A | --- | --- | 1.2 | V |
| t _{rr} | Reverse Recovery Time | V _{GS} =0V, I _S =60A, V _{DD} =50V, | --- | 220 | --- | nS |
| Q _{rr} | Reverse Recovery Charge | di _F /dt=100A/us | --- | 1.1 | --- | uC |

NOTES :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. V_{DD}=50V, L=0.3mH, R_G=25Ω, V_{GS}=10V.
3. The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%.
4. Essentially independent of operating temperature.

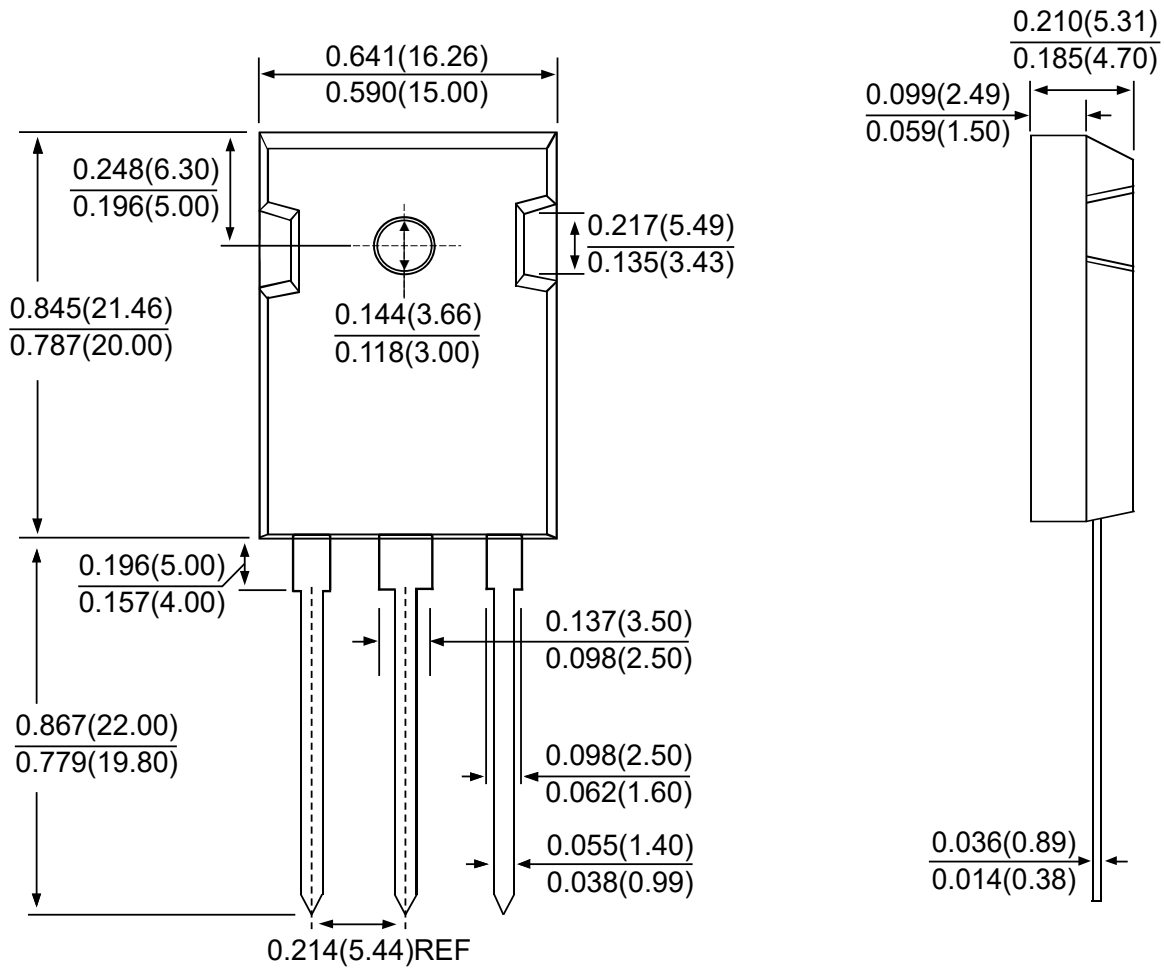


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Package Outline Dimensions



TO-247-3L

Dimensions in inches and (millimeters)



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